

Fig. 1

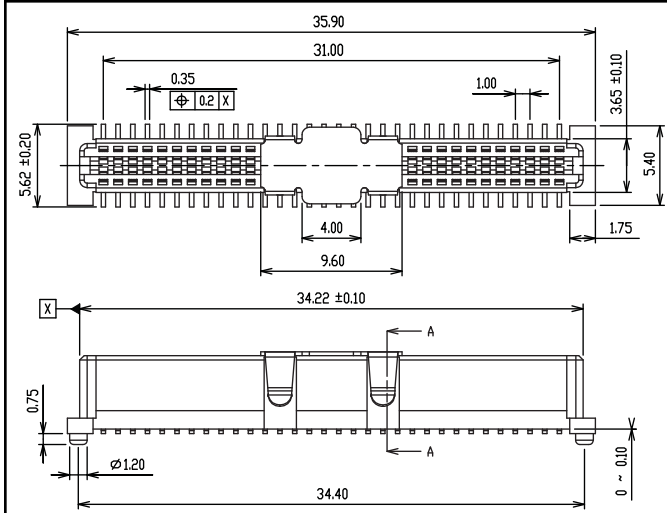
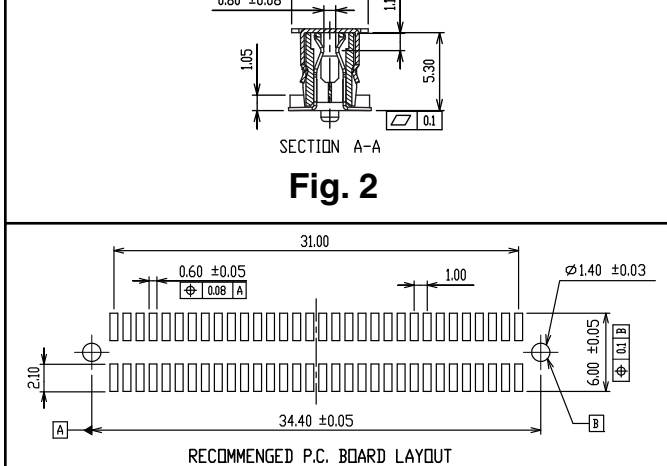
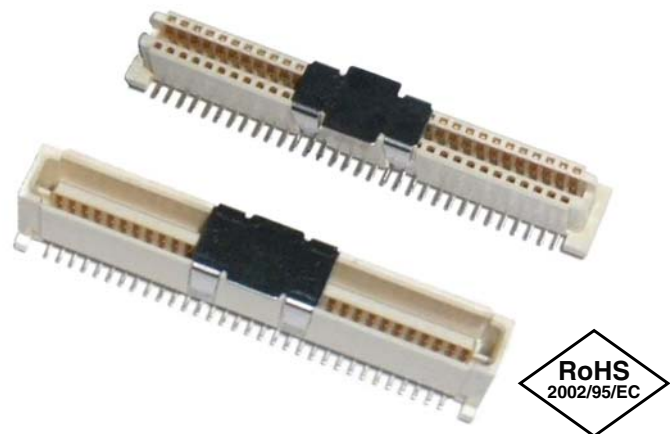


Fig. 2



RECOMMENDED P.C. BOARD LAYOUT



Features:

- 64 Position Mezzanine connectors for board stacking.
- 1 mm Centerline high density packaging.
- Mated connector board stacking height of 10 mm.
- Conforms to EIA-700 AAB for IEEE 1386 applications.
- Suitable for "lead free" reflow soldering (260° C peak).
- Tape & Reel packaged per EIA-783 (56 mm wide; 16 mm pitch).

Ordering Information:

Figure 1: 1mm Surface Mount Male Connector
891-10-064-30-120000

Packaging: 400 Parts per 330mm reel

Figure 2: 1mm Surface Mount Female Connector
893-43-064-30-420000

Packaging: 600 Parts per 330mm reel

Specifications:

Materials:

- Terminals & Contacts: Phosphor Bronze
- Plating: Contact area - 0,76µm Gold over nickel
- Solder Terminals - 1,9µm Tin over nickel
- Vacuum Cap: Stainless Steel
- Insulator Material: High temperature glass filled LCP, rated UL 94V-0

Ratings:

- Current: (30° C Temperature Rise): 0.5 A max., all circuits wired in series (1.0A max., five adjacent circuits wired in series)
- Voltage: 250V AC (RMS) (contact to contact)
- Operating Temperature range: -55° C - +85° C

Electrical:

- Contact resistance: 30mΩ max.
- Insulation resistance: 1,000 MΩ min.
- Dielectric Withstanding Voltage: 250V AC for one minute@sea level

Mechanical:

- Vibration: No discontinuity > 1 µs per MIL-STD 202, Method 201
- Physical Shock: No discontinuity > 1 µs per EIA 364-27 Test Condition H
- Durability: 100 Cycles min. per EIA 364-09
- Mating Force: 60 g/terminal max. per EIA 364-13
- Separation Force: 23 g/terminal min. per EIA 364-13
- Contact Retention Force: .4Kg min. per EIA 364-35

Environmental:

- Thermal Shock: Per EIA 364-32, Test Condition I
- Humidity: Test conditions - Ambient temp. 40±2°C; Relative humidity: 90 - 95%; Duration: 96 Hrs.
- Post Humidity inspection - 1. No damage
- 2. Contact resistance change < 15 mΩ
- 3. Insulation Resistance: 100 MΩ min.
- Solderability: Per EIA 364-52 Category 2